

TESTING, REPLACING, HANDLING, STORING, AND SHIPPING CIRCUIT PACKS AND SEMICONDUCTOR DEVICES

1. GENERAL

1.001 This addendum supplements Section 032-173-301, Issue 5. Place this pink sheet ahead of Page 1 of this section.

1.002 This addendum is issued to add a warning on Pages 6 and 7. This addendum does not affect the Equipment Test List.

2. CHANGES TO SECTION

2.001 On Page 6 after SHIPPING, add the following:

Warning: Do not ship circuit packs in ordinary cardboard or brown paper containers. Circuit packs shall be placed in containers which are free of corrosive constituents such as sulfur and chlorine. Enclosure in sealed polyethylene bags or equivalent is satisfactory for the inner pack.

2.002 On Page 6, revise paragraph 4.07 as follows.

4.07 Circuit packs and semiconductor devices are very fragile and must be carefully packed to prevent damage in shipment. When possible, the replacement unit shipping carton should be used to return the defective unit. If approved-type cartons are not available, units should be enclosed in individual polyethylene bags with zip type or twist type seals and then placed in standard shipping containers and tightly supported with crushed paper, paperwadding or foam pellets.

2.003 On Page 6, revise paragraph 4.08 as follows, but retain subparagraphs (1) and (2).

4.08 The shipping container for circuit packs should provide protection for the pack and its components. This container should protect the contact finish so that it is not scratched or contaminated with particulate matter or corrosive substances, such as sulphur or chlorides. Paper, wadding and cardboard cartons are common sources of these contaminants. Two suggested shipping containers are as follows:

2.004 On Page 7 after STORING add the following:

Warning: Do not store circuit packs in ordinary cardboard or brown paper containers. Circuit packs shall be placed in containers which are free of corrosive constituents such as sulfur and chloride. Enclosure in sealed polyethylene bags or equivalent is satisfactory for this purpose.

2.005 On Page 7, at the end of subparagraph 4.16(b), add the following.

(b.1) Corrosion of any exposed base metal such as copper in the gold plated contact area, such exposure can occur at pores in the gold due to wear. Corrosion at such sites is likely if circuit packs are wrapped for storage in brown paper, paperwadding or cardboard boxes.

NOTICE

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